



UNIVERSITY OF MICHIGAN
COLLEGE OF ENGINEERING
THE RADIATION LABORATORY
DEPARTMENT OF ELECTRICAL ENGINEERING
AND COMPUTER SCIENCE

3228 EECS BUILDING
1301 BEAL AVENUE
ANN ARBOR, MICHIGAN 48109-2122
734 764-0500 FAX 734 647-2106
<http://www.eecs.umich.edu/RADLAB/>

Re: Class II Permissive Change/Re-assessment
for Siemens Immobilizer
Models: 5WY7078, 5WY7250, 5WY7226,
5WY7330, 5WY7229
FCC ID: M3N5WY7078
IC: 267F-5WY7078

REQUEST FOR CONFIDENTIALITY

Pursuant to 47 CFR 0.459, Siemens requests that a part of the subject application be held confidential. This comprises Exhibits

- (5) Schematics
- (10) Parts List (Part of Exhibit only)

Siemens has spent substantial effort in developing this product and it is one of the first of its kind in industry. Having the subject information easily available to "competition" would negate the advantage they have achieved by developing this product. Not protecting the details of the design will result in financial hardship.

If there are any questions regarding this request, please contact me at the above address or call 734-483-4211, fax 734-647-2106 or e-mail liepa@umich.edu.

Sincerely,

A handwritten signature in black ink that reads 'Valdis V. Liepa'.

Valdis V. Liepa
Research Scientist
University of Michigan



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May 17, 2004

Re: Class II Permissive Change/Re-assessment
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STATEMENT OF MODIFICATIONS

There were no modifications made to the DUT by this test laboratory. (Also see Section 3.1 of the attached Test Report).

A handwritten signature in black ink that reads 'Valdis V. Liepa'.

Valdis V. Liepa
Research Scientist



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GENERAL PRODUCT INFORMATION

The device, for which certification is pursued, has been designed by:

Siemens Automotive Corporation
2400 Executive Hills Drive
Auburn Hills, Michigan 48326-2980 USA

Matthew Doyle
Tel: (248) 764-6724
Fax: (248) 764-7124

It will be manufactured by:

Siemens VDO S.A. de C.V.
Camino a la Tijera # 3,
Km 3.5 Carretera Guadalajara-Morelia
C.P. 45640 Mpio. Tlajomulco de Zúñiga, Jalisco Mexico

Matthew Doyle
Tel: (248) 764-6724
Fax: (248) 764-7124

Canadian Contact:

Siemens Automotive Ltd.
2775 St. Etienne Boulevard
Windsor ,ON N8W 5B1
Kurt Van Drus
Kurt.vandrus@siemens.com
1(519)974-5400
1(519)974-5401



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POWER OF ATTORNEY

A letter granting Valdis V. Liepa the Power of Attorney is on file and can be provided when so requested.



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CHANGES MADE

The current Immobilizer was modified as listed below:

Used original TPM type PCB to create all new versions.
Resonator changed to new foot print and frequency
TPM board and RKE / Immobilizer Only boards differ due to resonator foot prints
TPM board had flash capabilities added for the micro
TPM board micro die change (cut 1.9 to cut 1.B)